GND

RESET

TPS3809 ... DBV PACKAGE (TOP VIEW)

2

3

VDD

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- 3-Pin SOT-23 Package
- Supply Current of 9 μA (Typical)
- Precision Supply Voltage Monitor 2.5 V, 3 V, 3.3 V, 5 V
- Power-On Reset Generator With Fixed Delay Time of 200 ms
- Pin-For-Pin Compatible With MAX 809
- Temperature Range . . . –40°C to 85°C

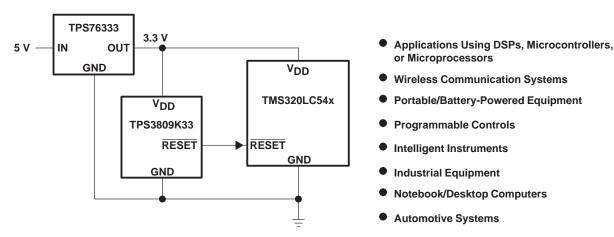
### description

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

During power-on, RESET is asserted when the supply voltage  $V_{DD}$  becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors  $V_{DD}$  and keeps RESET active as long as  $V_{DD}$  remains below the threshold voltage  $V_{IT}$ . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time,  $t_{d(typ)} = 200$  ms, starts after  $V_{DD}$  has risen above the threshold voltage  $V_{IT}$ . When the supply voltage drops below the threshold voltage  $V_{IT}$ , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed sense-threshold voltage  $V_{IT}$  set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23. The TPS3809 devices are characterized for operation over a temperature range of  $-40^{\circ}$ C to  $85^{\circ}$ C.

## typical applications





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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AVAILABLE OPTIONS								
TA	DEVICE	NAME	THRESHOLD VOLTAGE	MARKING				
	TPS3809J25DBVR <sup>†</sup>	TPS3809J25DBVT‡	2.25 V	PCZI				
40°C to 95°C	TPS3809L30DBVR <sup>†</sup>	TPS3809L30DBVT <sup>‡</sup>	2.64 V	PDAI				
–40°C to 85°C	TPS3809K33DBVR <sup>†</sup>	TPS3809K33DBVT <sup>‡</sup>	2.93 V	PDBI				
	TPS3809I50DBVR <sup>†</sup>	TPS3809I50DBVT‡	4.55 V	PDCI				

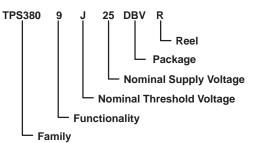
<sup>†</sup> The DBVR passive indicates tape and reel of 3000 parts.

<sup>‡</sup> The DBVT passive indicates tape and reel of 250 parts.

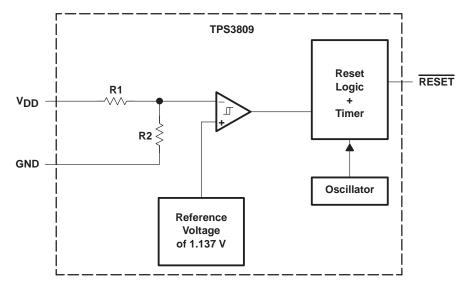
## FUNCTION/TRUTH TABLE, TPS3809

V <sub>DD</sub> >V <sub>IT</sub>	RESET
0	L
1	н

#### ORDERING INFORMATION



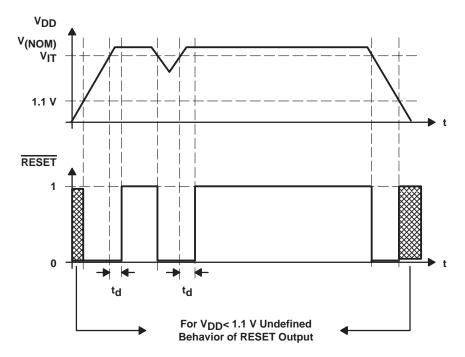
## functional block diagram





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## timing diagram



## absolute maximum ratings over operating free-air temperature (unless otherwise noted)<sup>†</sup>

Supply voltage, V <sub>DD</sub> (see Note1)	
All other pins (see Note 1)	
Maximum low output current, I <sub>OL</sub>	5 mA
Maximum high output current, IOH	
Input clamp current, I <sub>IK</sub> (VI<0 or VI>VDD)	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> <0 or V <sub>O</sub> >V <sub>DD</sub> )	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	–40°C to 85°C
Storage temperature range, T <sub>stg</sub>	
Soldering temperature	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation the device should not be operated at 7 V for more than t=1000h continuously.

DISSIPATION RATING TABLE						
PACKAGE	T <sub>A</sub> <25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING		
DBV	437 mW	3.5 mW/°C	280 mW	227 mW		

## recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V <sub>DD</sub>	2	6	V
Operating free-air temperature range, T <sub>A</sub>	-40	85	°C



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electrical characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise noted)					•	•	

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT			
			V <sub>DD</sub> = 2.5 V to 6 \	/, I <sub>OH</sub> = –500 μA	V <sub>DD</sub> -0.2					
Vон	High-level output voltage		V <sub>DD</sub> = 3.3 V,	I <sub>OH</sub> = -2 mA	V <sub>DD</sub> -0.4			V		
			V <sub>DD</sub> = 6 V,	I <sub>OH</sub> = -4 mA	V <sub>DD</sub> -0.4					
			$V_{DD} = 2 V \text{ to } 6 V,$	I <sub>OL</sub> = 500 μA			0.2			
VOL	Low-level output voltage		V <sub>DD</sub> = 3.3 V,	I <sub>OL</sub> = 2 mA			0.4	V		
			V <sub>DD</sub> = 6 V,	I <sub>OL</sub> = 4 mA			0.4			
	Power-up reset voltage (see Note a	2)	$V_{DD} \ge 1.1 V$ ,	I <sub>OL</sub> = 50 μA			0.2	V		
		TPS3809J25			2.20	2.25	2.30			
\/. <del></del>	Negative-going input threshold	TPS3809L30		2.58	2.64	2.70	v			
VIT–	voltage (see Note 3)	TPS3809K33	$T_A$ – 40°C to 85°C		2.87	2.93	2.99	v		
		TPS3809I50			4.45	4.55	4.65			
		TPS3809J25				30				
<b>M</b> .	Hyptorogia	TPS3809L30	]			35		mV		
V <sub>hys</sub>	Hysteresis	TPS3809K33	]			40		mv		
		TPS3809I50				60				
	Supply ourrest		V <sub>DD</sub> = 2 V, Outpu	ut unconnected		9	12			
IDD	Supply current		V <sub>DD</sub> = 6 V, Outpu	ut unconnected		20	25	μA		
Ci	Input capacitance		$V_I = 0 V \text{ to } V_{DD}$			5		pF		

NOTES: 2. The lowest supply voltage at which  $\overrightarrow{\text{RESET}}$  becomes active.  $t_{r, VDD} \ge 15 \,\mu\text{s/V}$ . 3. To ensure best stability of the threshold voltage, a bypass capacitor (  $0.1 \,\mu\text{F}$  ceramic) should be placed near the supply terminals.

# timing requirements at R\_L = 1 M\Omega, C\_L = 50 pF, T\_A = 25°C

	PARAMETER TEST CONDITIONS				MIN	TYP	MAX	UNIT	
t	w I	Pulse width	at V <sub>DD</sub>	$V_{DD} = V_{IT-} + 0.2 V,$	$V_{DD} = V_{IT-} - 0.2 V$	3			μs

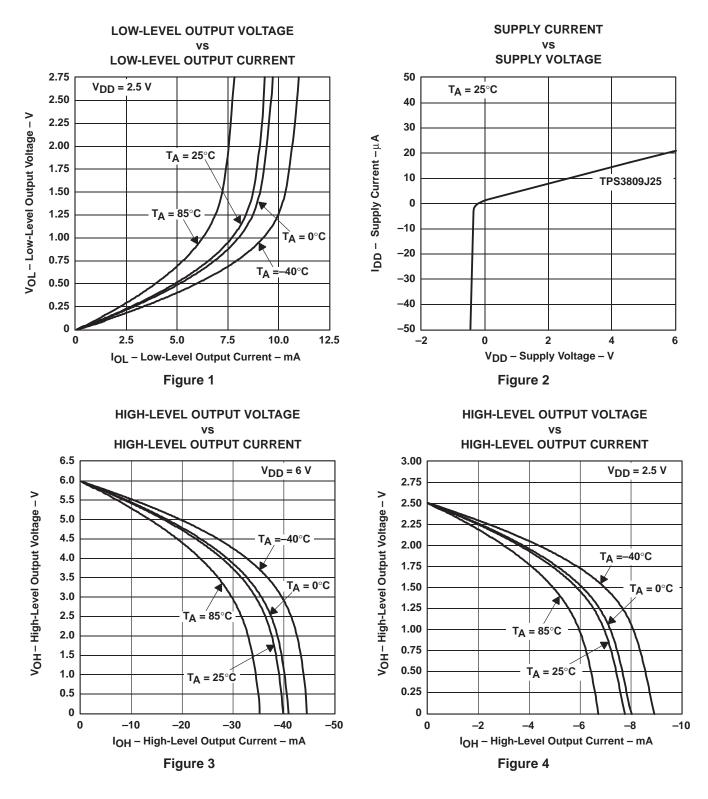
# switching characteristics at R<sub>L</sub> = 1 MΩ, C<sub>L</sub> = 50 pF, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
td	Delay time		$V_{DD} \ge V_{IT-} + 0.2 V$ , See timing diagram	120	200	280	ms
<sup>t</sup> PHL	Propagation (delay) time, high-to-low-level output	V <sub>DD</sub> to RESET delay	$V_{IL} = V_{IT-} - 0.2 \text{ V},$ $V_{IH} = V_{IT-} + 0.2 \text{ V}$		1		μs



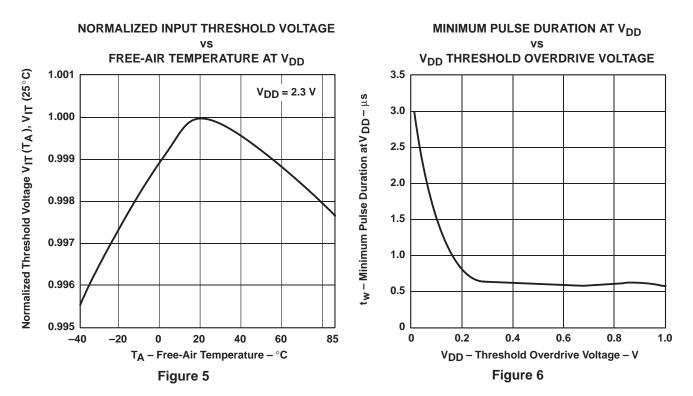
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## **TYPICAL CHARACTERISTICS**





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**TYPICAL CHARACTERISTICS** 

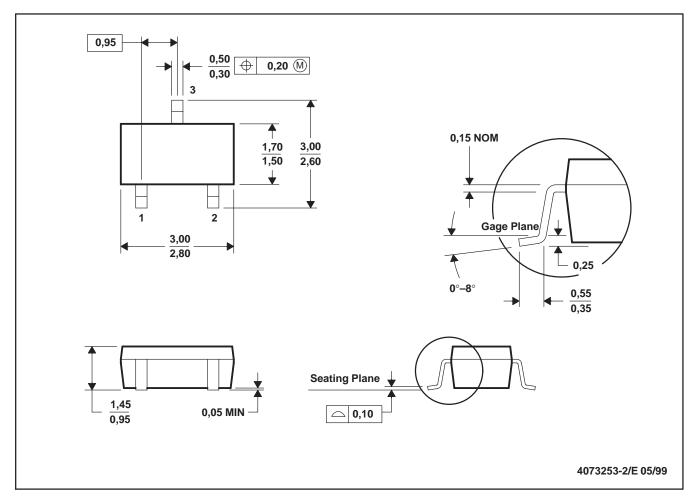


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MECHANICAL DATA

## PLASTIC SMALL-OUTLINE

DBV (R-PDSO-G3)



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.



4-Mar-2005

## **PACKAGING INFORMATION**

JMENTS

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Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(3)</sup>
TPS3809I50DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809I50DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809I50DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809I50DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809J25DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809J25DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809J25DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809K33DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS3809L30DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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